

Mission Critical – The importance of clear problem statements for Innovation Engineering

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MaaS / TaaS HW/SW
Development



Commercial
Vehicles

What do we want?

Shaping the future of autonomous mobility SW-Driven-BMs

Configurable, flexible platform for SW based services fully compliant to the digital IoT ecosystem

Autonomous Driving

Level 5
Fully
automated



Level 4
Highly
automated



In ODD



Level 3
Partially
automated



Level 2
Today's driver
assistance systems



Level 1
Base level
assistance systems



Level 0
Driver only



Mobility-as-a-Service



Digital Urban Mobility

- ▶ Door-to-door, efficient & safe
- ▶ Shared mobility vs. ownership
- ▶ Traffic relief through pooling

Transport-as-a-Service



Goods Transport of Tomorrow:

- ▶ Efficiency gains in the last mile
- ▶ Response to driver shortage
- ▶ Flexible use 24/7, 365 days/year

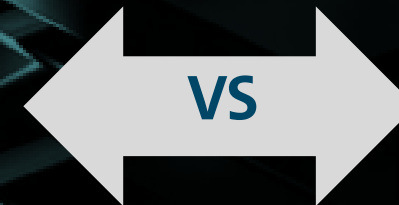
MaaS/TaaS vehicles operate fully autonomous

in a limited Operational Design Domain (ODD)

L2+/L3 private-use

L4 AD MaaS/ TaaS

Limitation to specific road classes → fragmented ODD



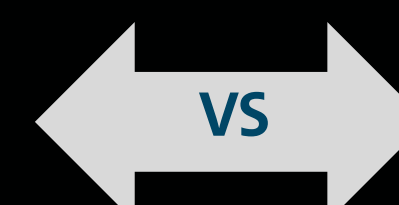
Continuous operations with the ODD

Handover to driver to cover system limits



Remote guidance in rare unclear traffic situations

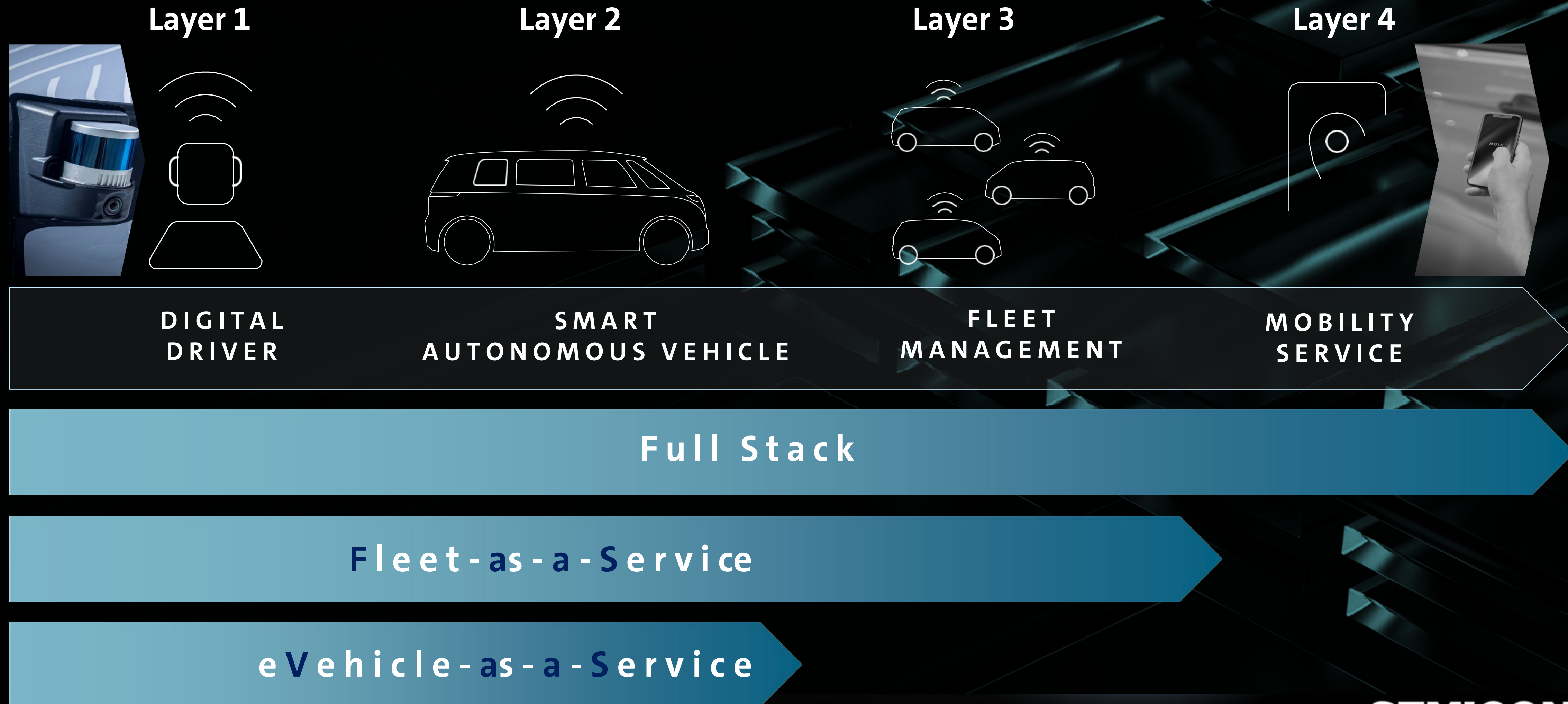
Mainly highway



Urban focus

Modular solutions tailored to customer needs

- cities, service operators, logistic firms ...



Where do we come from?

Automotive – many semiconductors & high product complexity

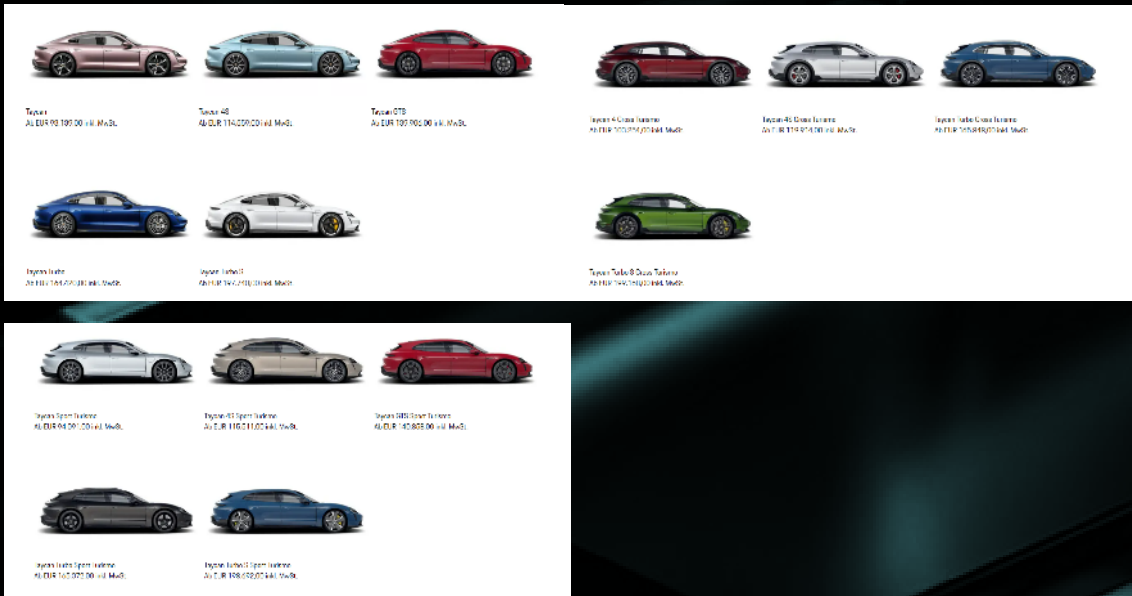
Apple
iPhone 15



SONY
PlayStation 5



Porsche
Taycan



Number of
main variants¹

4

2

14

Units sold
per year

~ 225.000.000

~ 19.000.000

~ 44.000

Number of
semiconductors

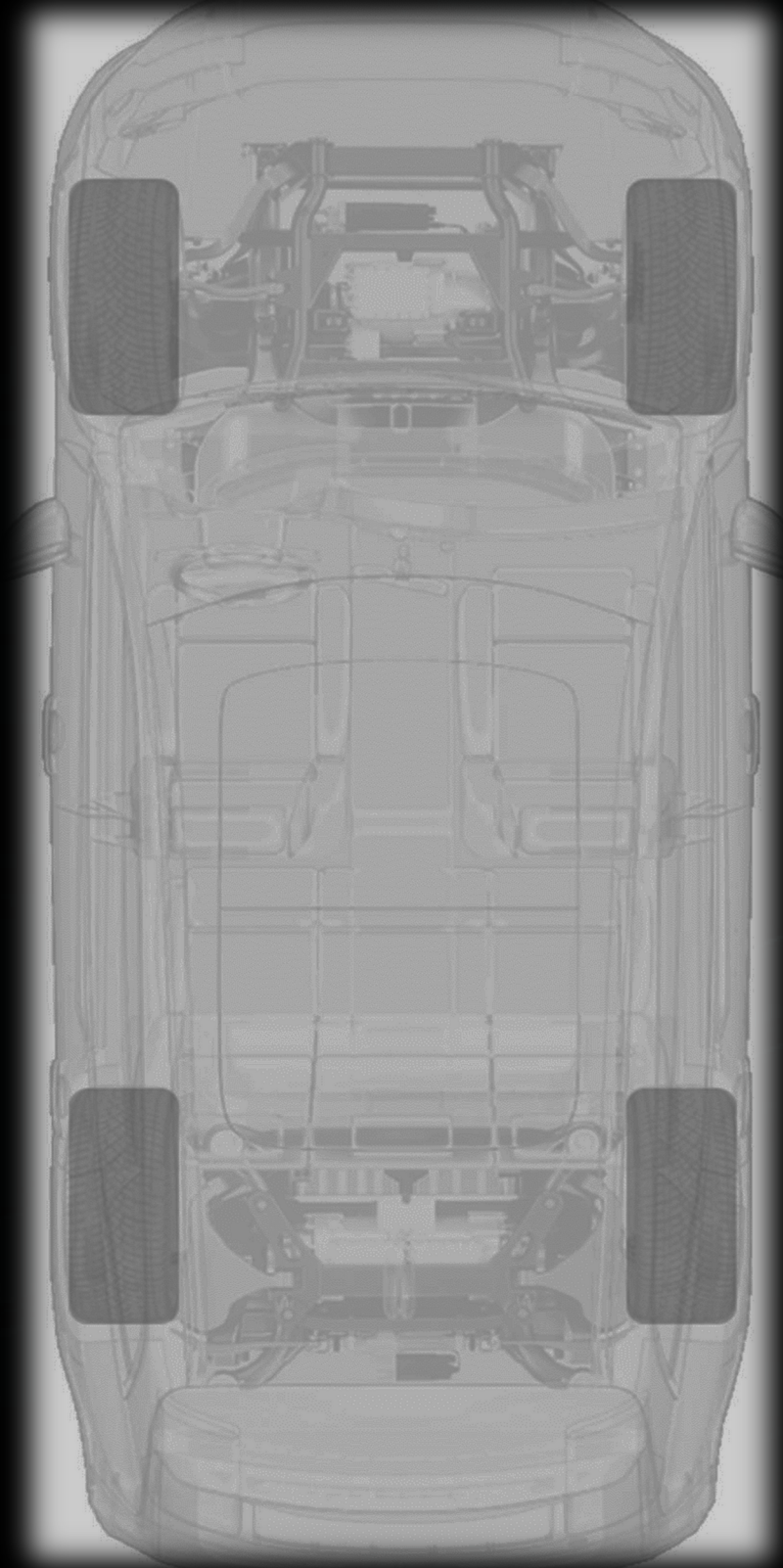
Approx. 35¹

Approx. 130¹

Approx. 8.000¹

1: based on Porsche Consulting teardown

Automotive – product complexity & tech node capacity competition



NODE SIZE	2022	2026	CAGR*		TREND**
			Demand	Capacity	
> 250 nm	● ● ●	● ● ●	+2.4%	+0.0%	↘
> 180 nm	●	● ●	+3.3%	-0.7%	↘
> 130 nm	●	●	+3.4%	-0.7%	↘
> 90 nm	●	● ●	+3.1%	-1.4%	↘
> 45 nm	●	●	-1.3%	+3.7%	↗
> 28 nm	●	●	+7.3%	+3.1%	→
> 16 nm	●	●	-10.7%	-7.0%	→
> 10 nm	●	●	+8.4%	+5.7%	↘
≤ 10 nm	●	●	+18.3%	+16.6%	→

● No shortage ● Minor shortage ● ● Medium shortage ● ● ● Major shortage

* Compound annual growth rate 2022–2026 |

** Based on development 2022–2026, subject to creation of further new capacities

Source: omdia, Q3/2022 Silicon Market Trackers, Porsche Consulting Analysis

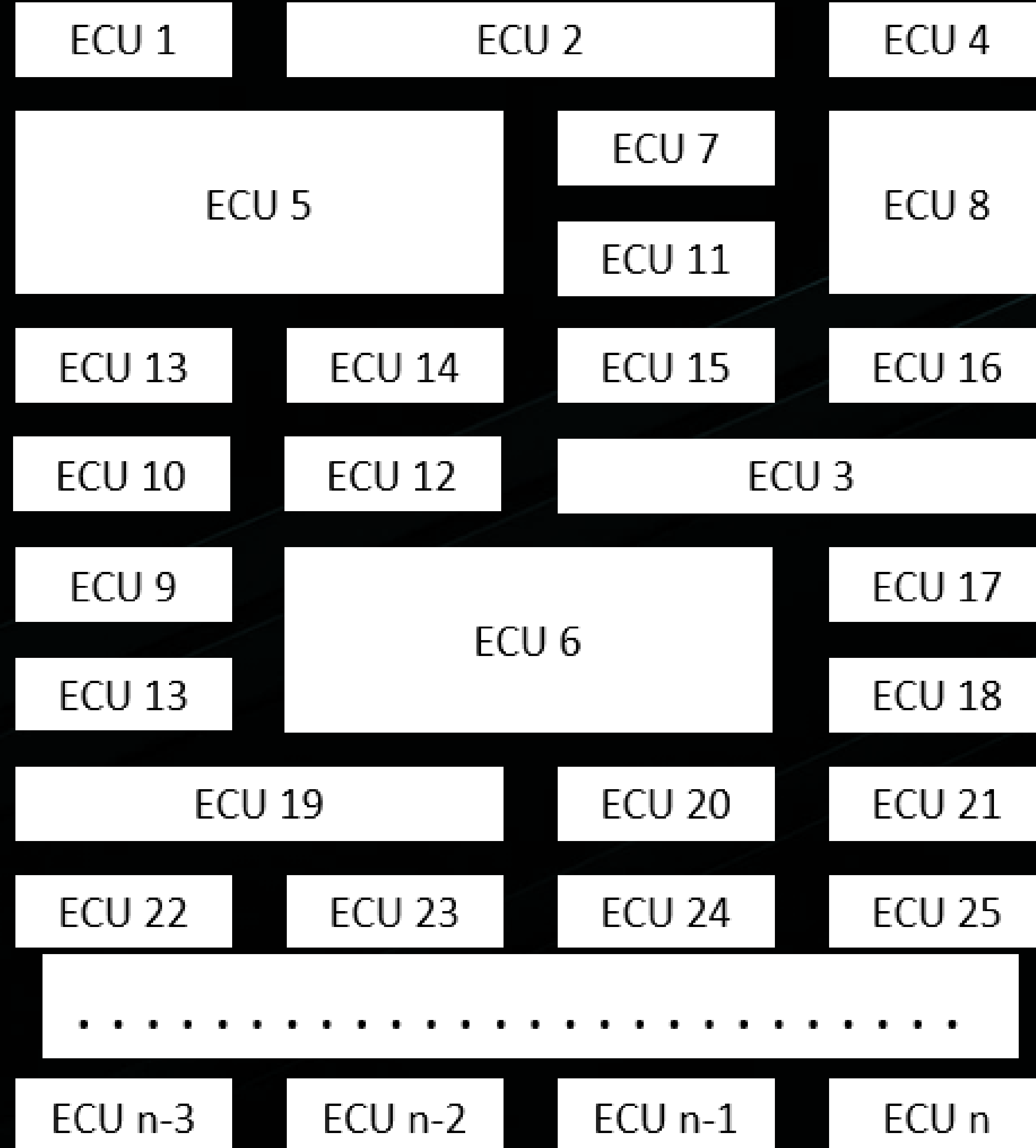


Automotive – product complexity & tech node capacity competition

Classical proprietary
black box Tier1 ECU
design mismatch

leads to increased

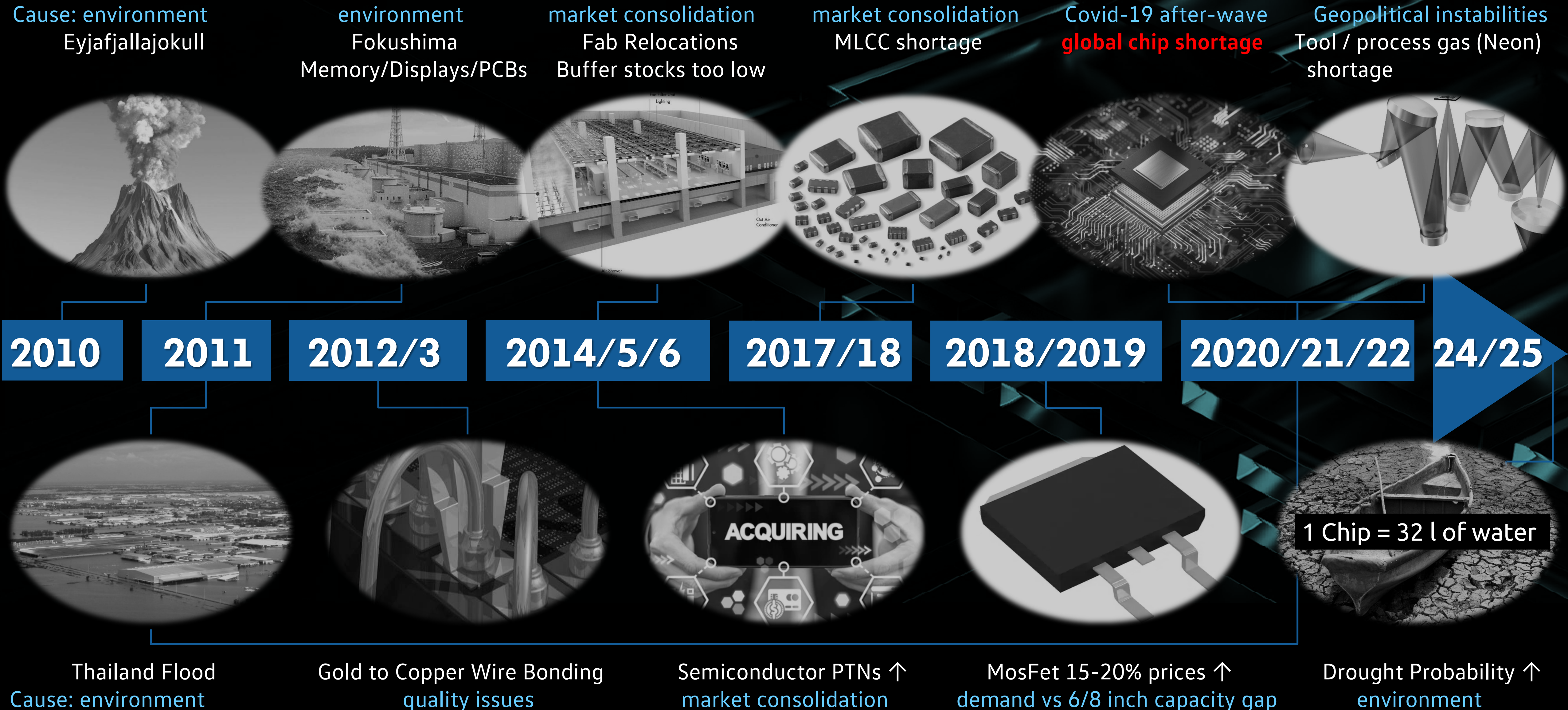
vulnerability during
supply chain
disruptions



Selected automotive electronics shortages – flashback & outlook

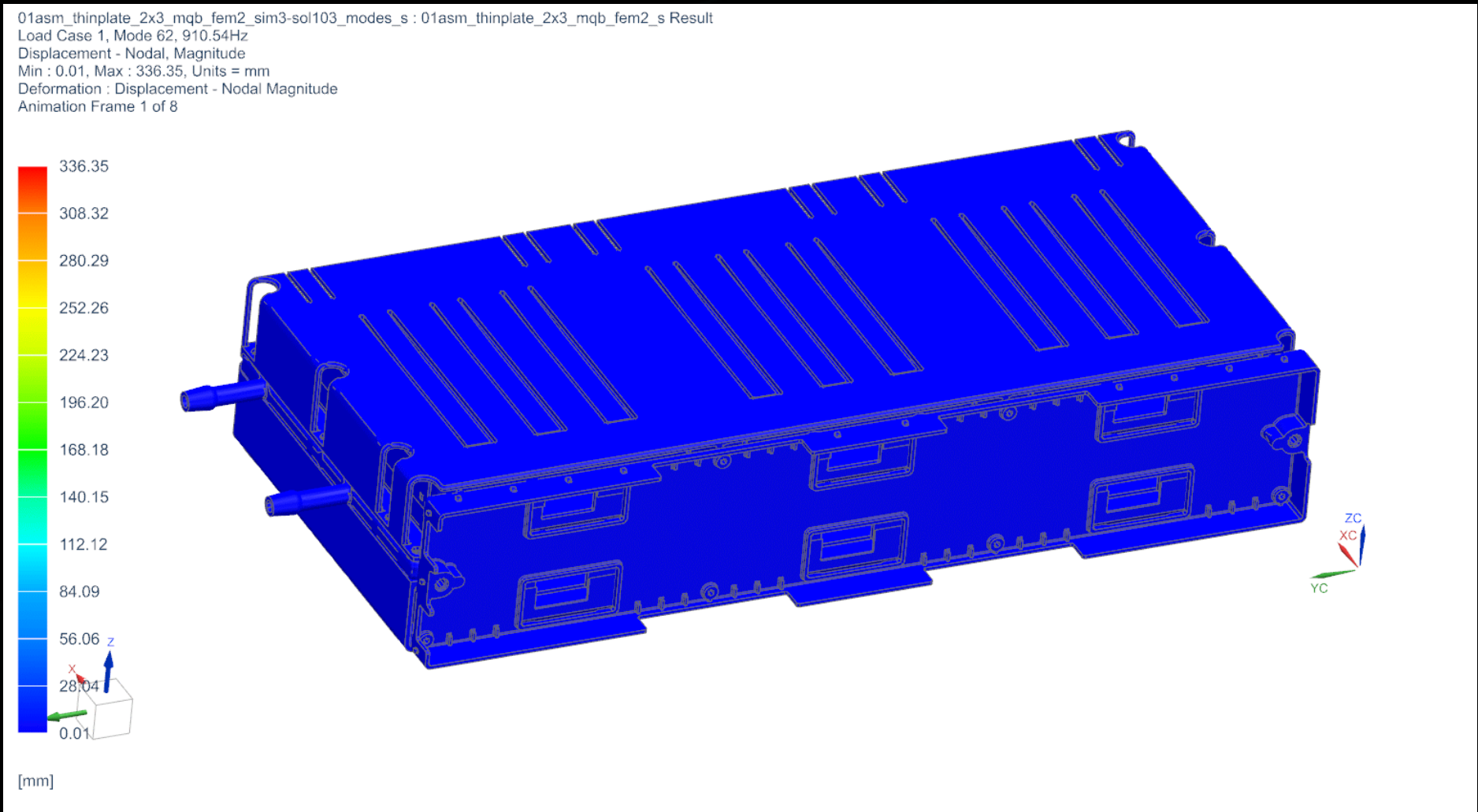
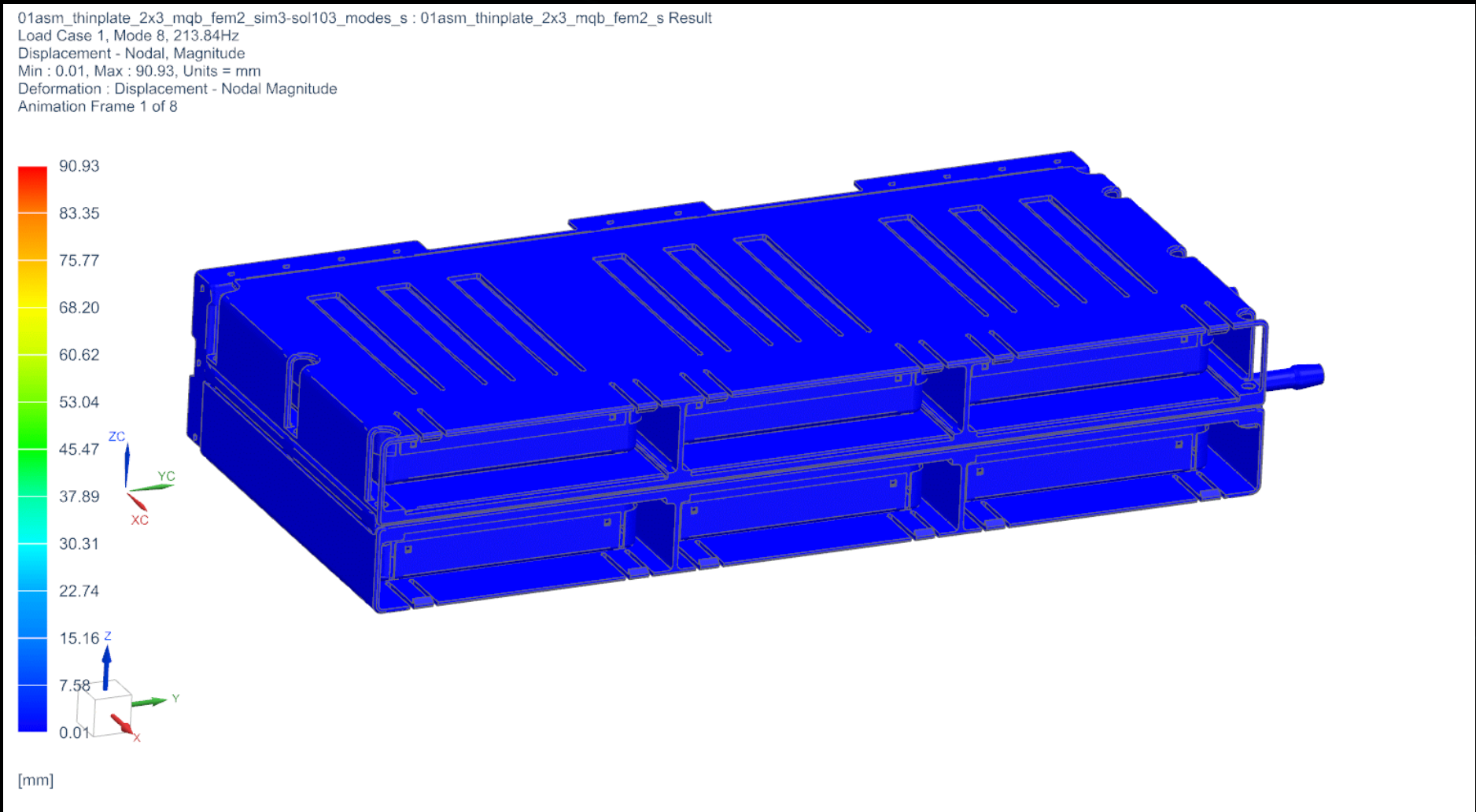
LL: shortages are a regular part of the industry - are they managed sufficiently?

A. Aal, SEMICON EUROPA, FMF, 2022

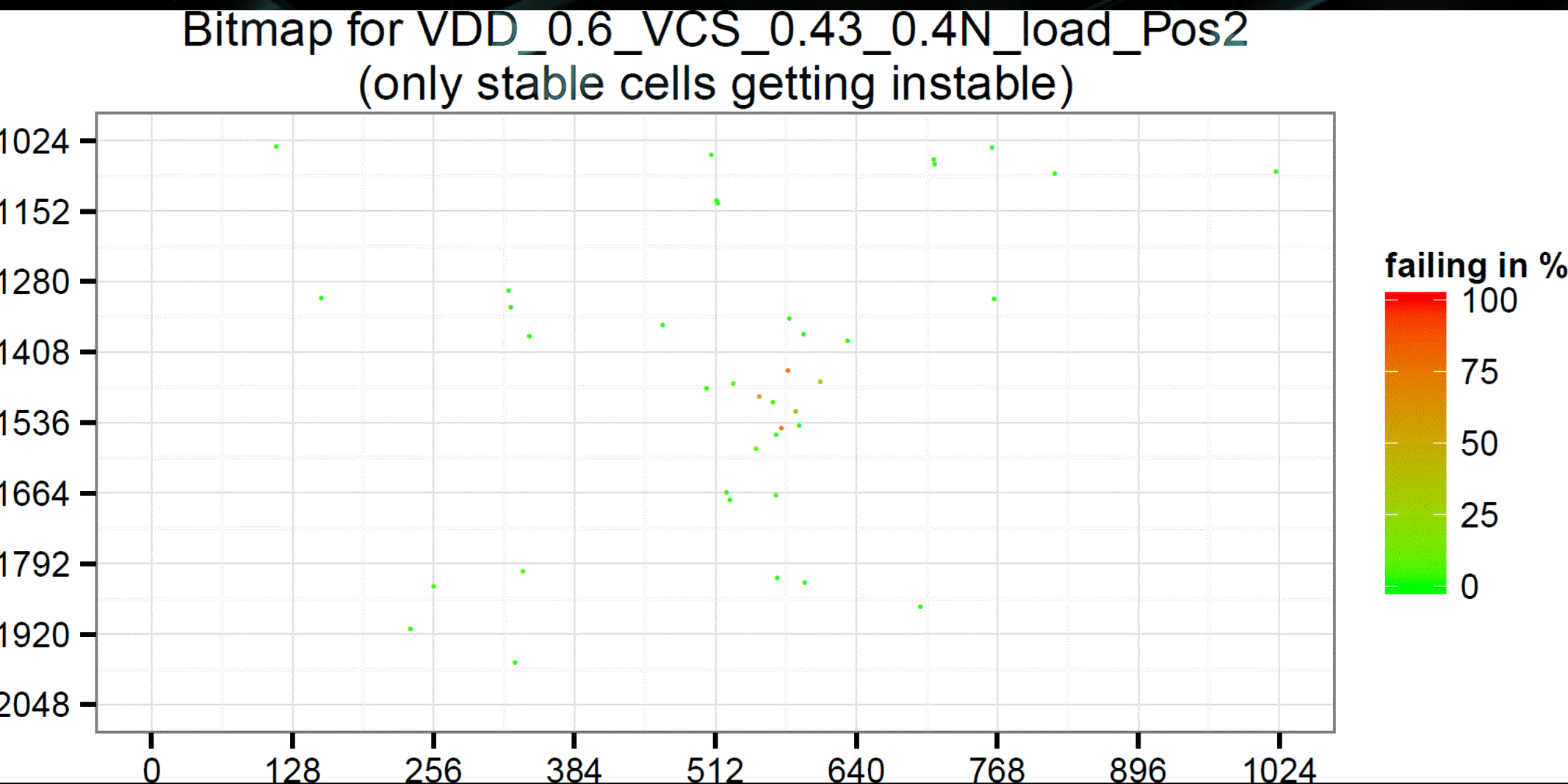
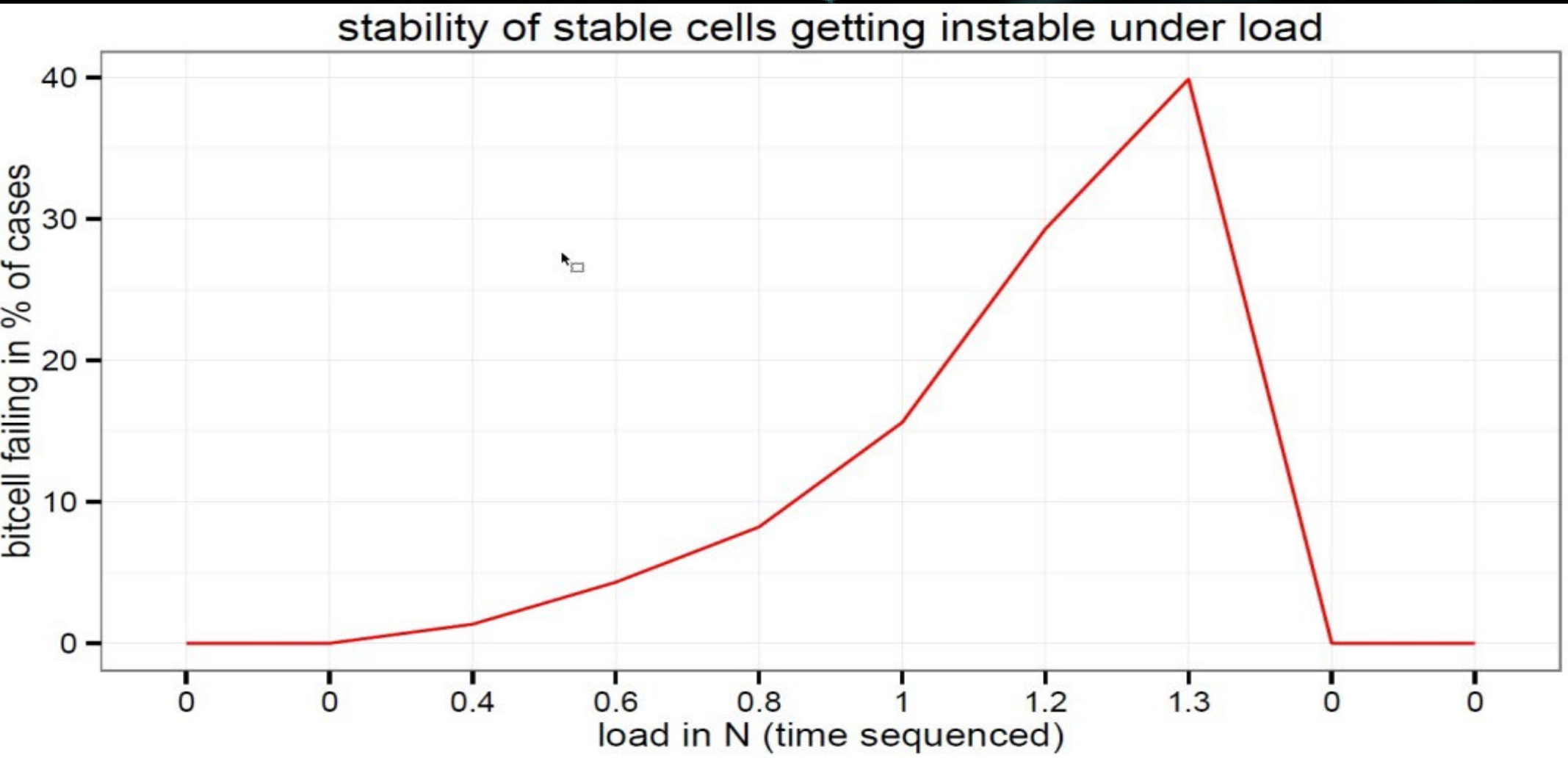


Automotive – Integration complexity

- SRAM read disturb due to mechanical stress



A. Aal et. al., Reliability & Stress-Related Phenomena in Nano-electronics 2016



What we do? – inferring
requirements and designing
architectures

Automotive Digital Business Models

... force a change of the E/E architecture towards **SDVs**

A. Aal, CENEX, UK, 2023

Market Expectations

- Autonomous Driving
- Smart Infotainment
- Seamless Multimedia
- Augmented Reality
- Digital Business Models
- Environ. Compliance

New in-vehicle compute system enables
Software-Driven Business Models



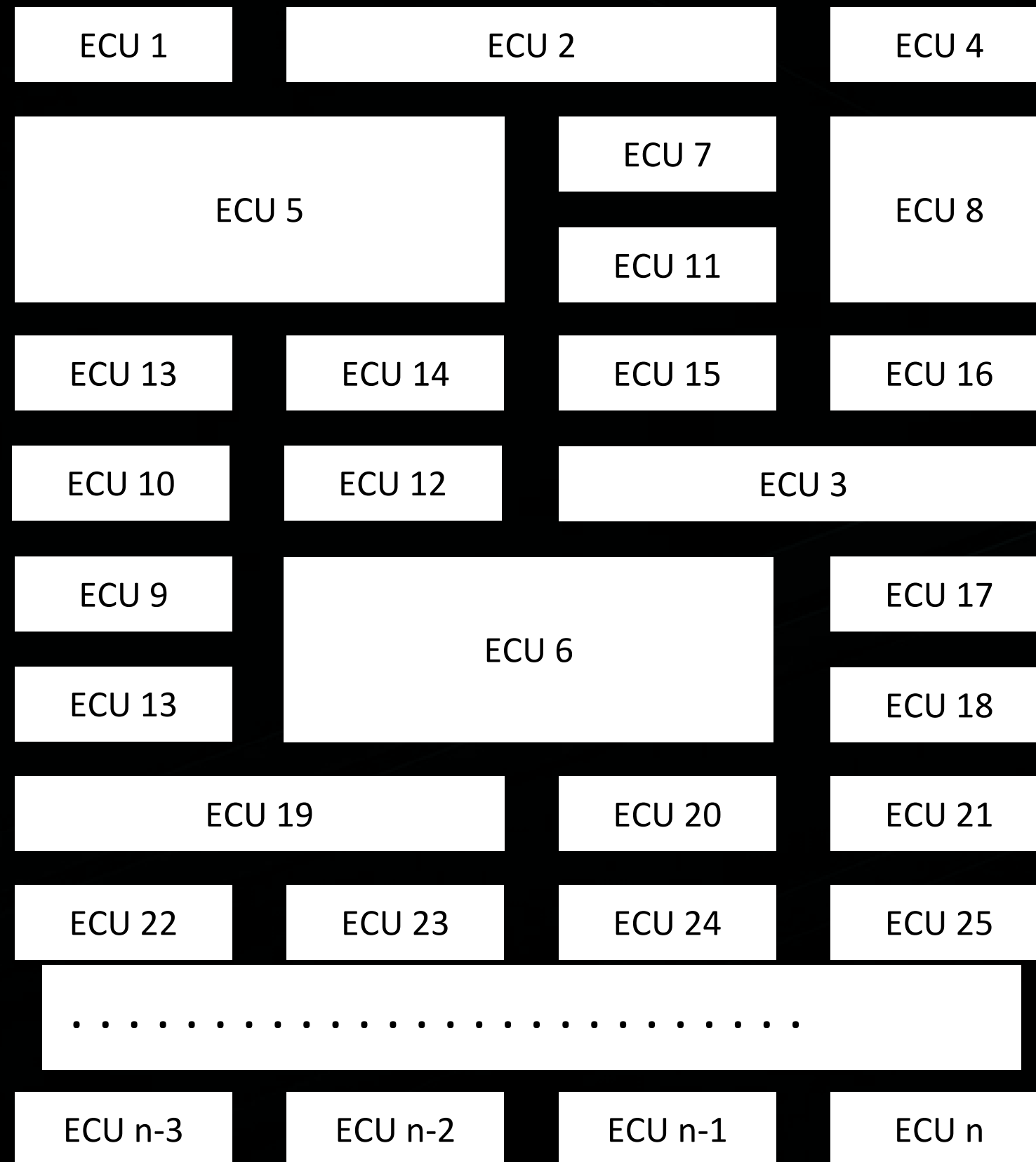
Require

- ✓ *Safety / Reliability*
- ✓ *Cyber Security*
- ✓ Software Updates
- ✓ Hardware Upgrades
- ✓ Short Time-to-Market
- ✓ Best Cost/Performance

Target offer – flexible & securely encapsulated customer platform for SW based services

SDV – SHIFT FROM MULTI ECU

- TOWARDS CENTRALIZED OR DOMAIN COMPUTE PLATFORMS – DISRUPTIVE TRANSFORMATION –

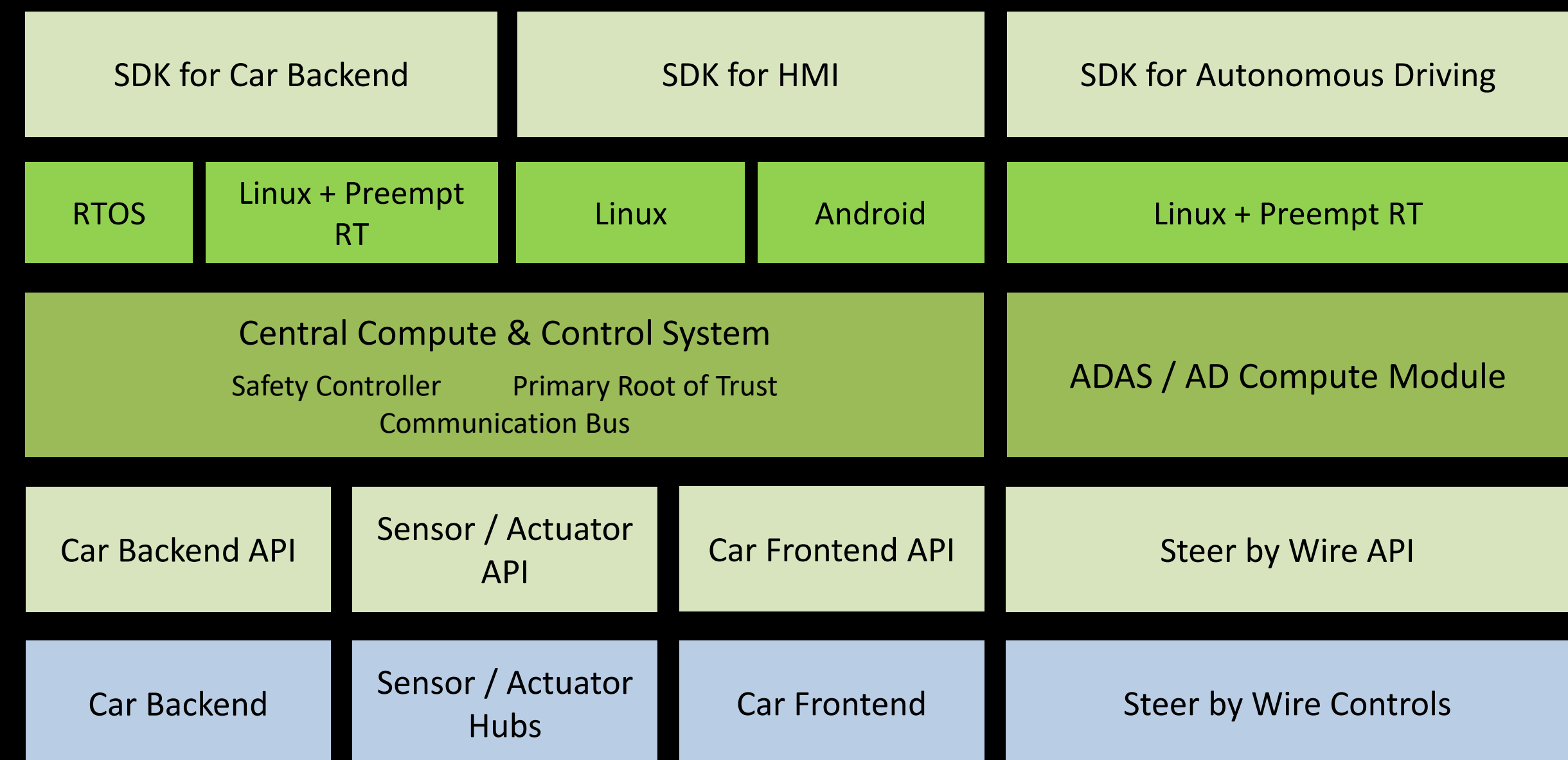


- Open Blackboxes
- Control Value Chain
- Drive Innovation



~~ECU~~

Compute Platform



SDV ARCH ADAPTION – **CHIPLETS CAN ONLY COMPLEMENT, HERE !!!** – TARGET DEFINITION – THE “EIERLEGENDE WOLLMILCHSAU (GERMAN), WHY?”



SYSTEMS ENGINEERING GUIDED ARCHITECTURE CHANGE

– HPC & AI ARCH REQUIREMENTS –

High level (AI) compute architecture requirements for SDVs*):

- Modular, re-configurable to train algorithms
- Predictable & time constrained (safety, real time)
- Reliable / fault tolerant
- Flexible: Neural Network algorithm agnostic
- Fail safe towards surrounding systems
- Resource / energy efficient

*SDV: Software Defined Vehicles (SDV) build a subclass of Software Defined Systems (SDS)

- designed following a development methodology where SW & HW are malleable & defined in parallel
- along with connectivity to iteratively ensure the platform under development meets system-aware requirements
- optimal solution measured by flexibility, performance, cost, manufacturability, reliability, safety

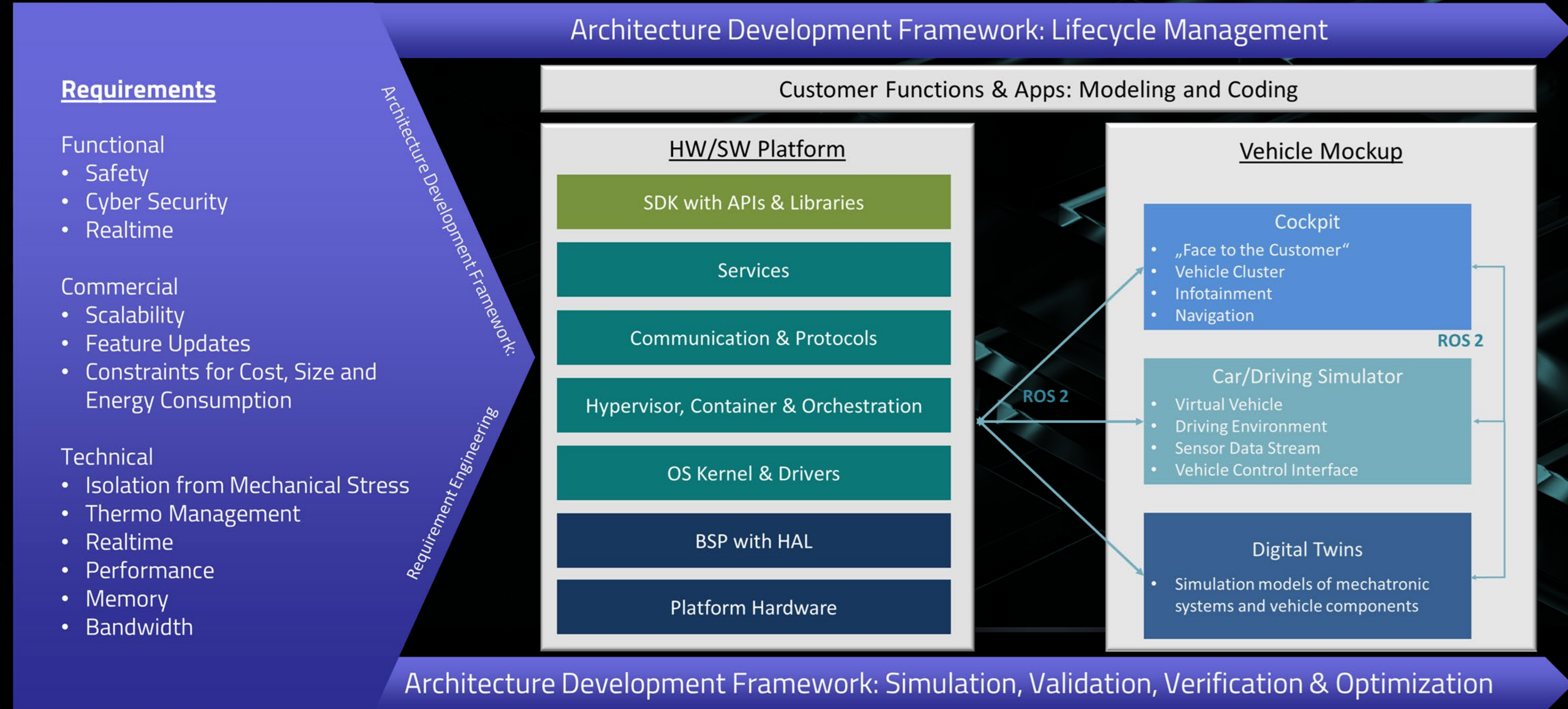
Note: System design for Inference $\neq$ design for training

- 1 bit flip $\rightarrow$ 100 x failure in the AI model
- AI training can cause load mission profiles similar to row hammer attacks $\rightarrow$ CS

THE SUM OF ALL CO-DEVELOPMENT IS THE PRODUCT

- ΣΠ FRAMEWORK

Digital Twinning



NEW SDV ARCHITECTURE APPROACH

– ADVANCE ACCELERATION LOGIC – IMPLEMENTABLE THROUGH MODULE AND/OR CHIPLET MODULES

- New architecture combination of NoC & multi-compute IP based engines
 - ASIL-D compliant
 - integrated compute cluster and newly integrated construction code (ICC – in car cloud) – energy efficient and super robust reimplementation of an edge-server for ISS (innovation solution services)
 - Spatial multi-redundant architecture that controls data flow by assigning data based on AI algorithm attributes to the most suitable IP + balancing CE (compute engine) workload for optimized performance and efficiency (longer lifetime, reduced hot spots, less cooling power) / minimal energy consumption
 - MMHMRIOV (managed multi host multi root IO virtualization implementation)
- Different types of CEs (CPU, GPU, NPU, DSP) – general purpose with high specialization option through configurability by main CE-fabric
- Read/write operations consume most power in AI algorithm deployment → architecture task to reduce those

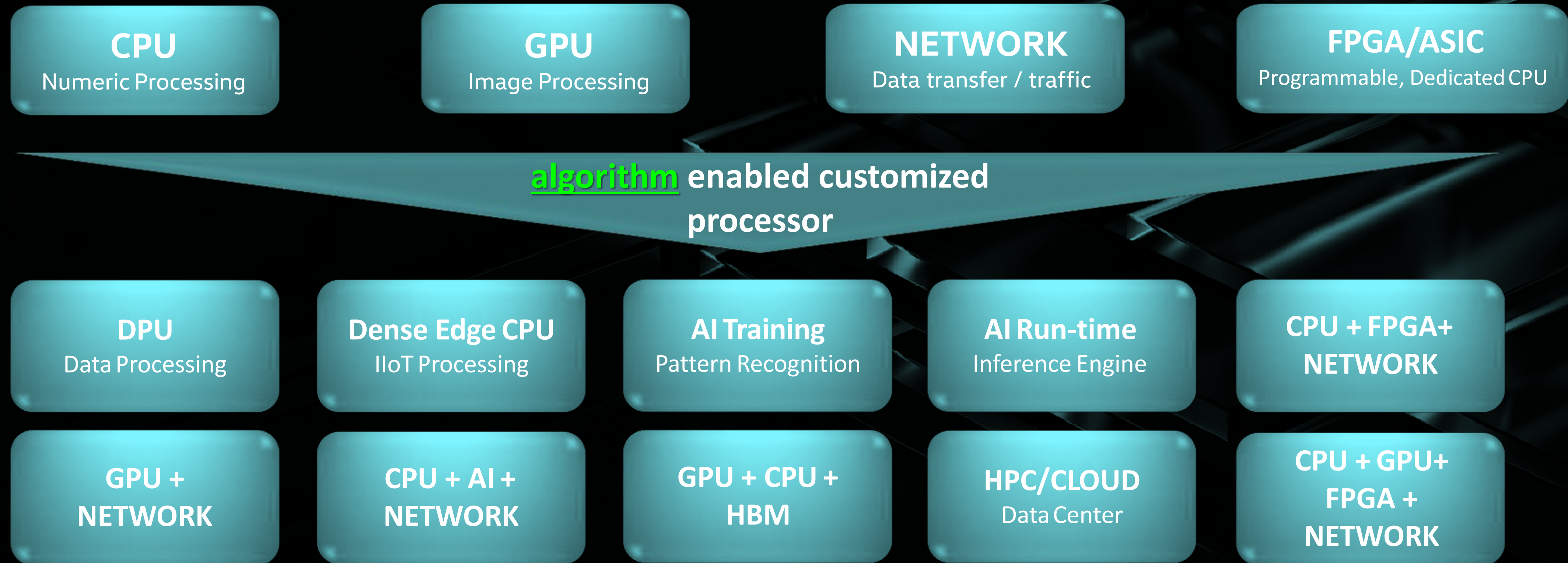
Principle of HW offloading extended to AI-SW algorithm offloading

Whom do we need? – a
matching partner ecosystem

COLLABORATION

OPTIMIZED SDV ALGORITHM DECOMPOSITION

- PARALLEL PROCESSING @ MOST SUITABLE ACCELERATOR IP



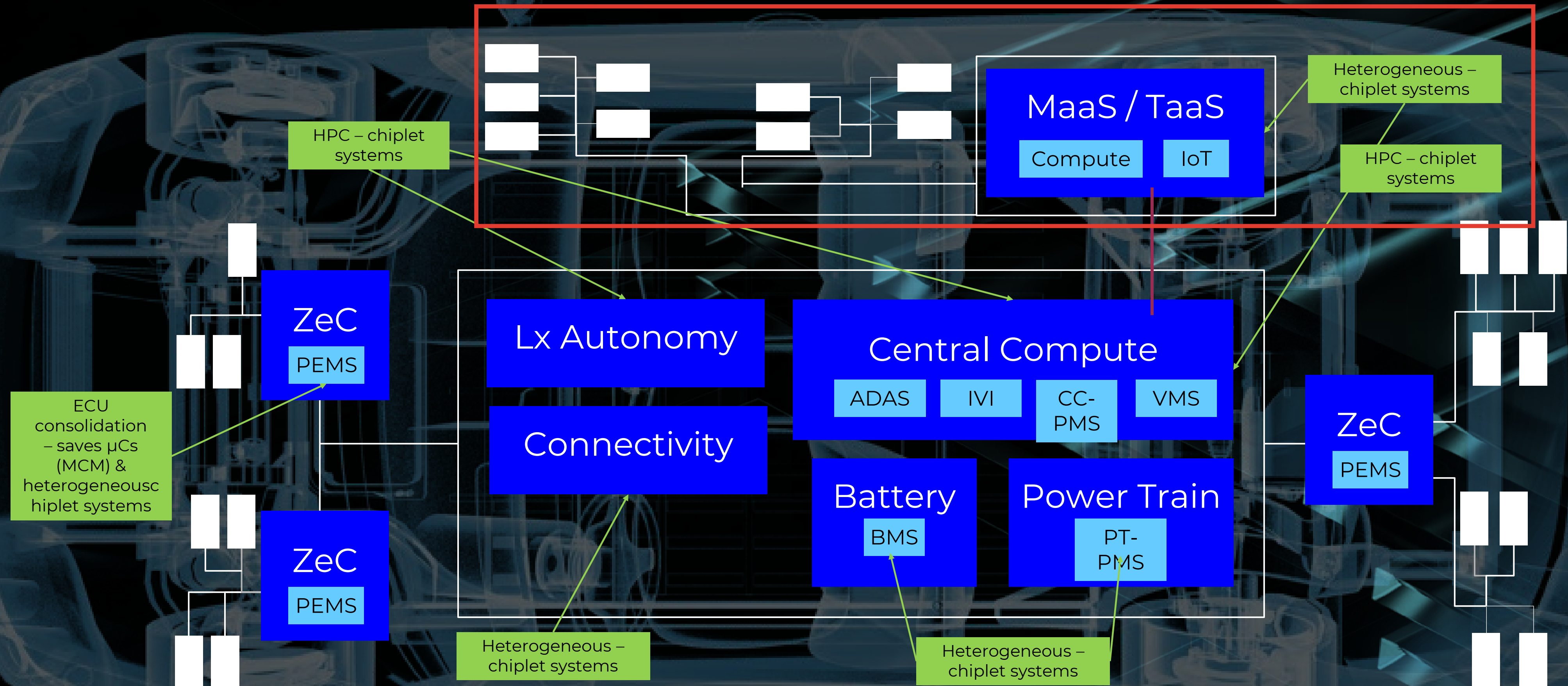
SDV Architecture optimization potential through applying suitable Chiplet system architectures

We are Looking for the right collaboration !!!

SYS-ENG OPTIMIZED CHIPLLET USAGE IN AUTOMOTIVE

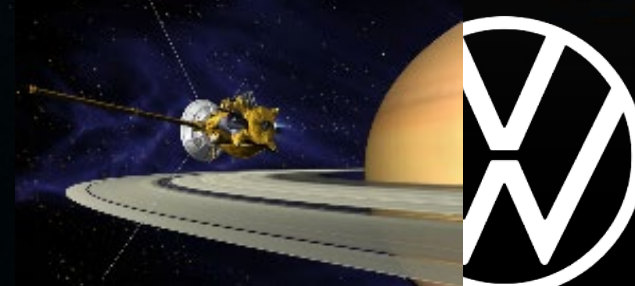
APPLICATION DOMAIN & ARCHITECTURE DOMAIN RELATED

Let's collaborate





Whom or whatever you need to transport – our future platform adjusts our vehicles to your business on any planet.



SEMICON **EUROPA** 50 YEARS